

ABSTRACT

An object of the invention is to provide an etching solution composition which adds an excellent etched surface morphology to a metal to be etched at a suppressed etch rate. The invention relates to an etching solution composition which is obtained by blending at least (A) nitric acid, (B) acetic acid, (C) a phosphorus compound and (D) water and in which the water concentration after blending is 3.0 M or less.

Fig. 2